

### Description

The XSD07C is a bi-directional TVS diode, utilizing leading monolithic silicon technology to provide fast response time and low ESD clamping voltage, making this device an ideal solution for protecting voltage sensitive data and power line. The XSD07C complies with the IEC 61000-4-2 (ESD) with  $\pm 30\text{kV}$  air and  $\pm 30\text{kV}$  contact discharge. It is assembled into an ultra-small SOD-323 lead-free package. The small size and high ESD surge protection make XSD07C an ideal choice to protect cell phone, digital cameras, audio players and many other portable applications.

### Features

- Protects one data or power line
- Ultra low leakage: nA level
- Operating voltage: 7V
- Low clamping voltage
- Complies with following standards:
  - IEC 61000-4-2 (ESD) immunity test
    - Air discharge:  $\pm 30\text{kV}$
    - Contact discharge:  $\pm 30\text{kV}$
  - IEC61000-4-5 (Lightning) 20A (8/20 $\mu\text{s}$ )
- RoHS Compliant

### Mechanical Characteristics

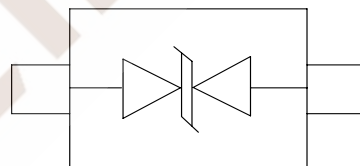
- Package: SOD-323
- Lead Finish: Matte Tin
- Case Material: "Green" Molding Compound.
- Terminal Connections: See Diagram Below
- Marking Information: See Below

### Applications

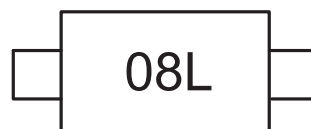
- Cellular Handsets and Accessories
- Personal Digital Assistants
- Notebooks and Handhelds
- Portable Instrumentation
- Digital Cameras
- Peripherals
- Audio Players
- Keypads, Side Keys, LCD Displays



SOD-323



Circuit diagram



08L= Device code  
Marking (Top View)

### Ordering Information

| Part Number | Packaging        | Reel Size |
|-------------|------------------|-----------|
| XSD07C      | 3000/Tape & Reel | 7 inch    |

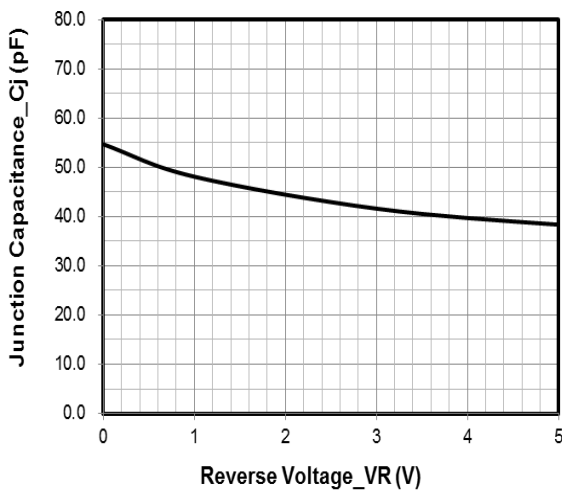
**Absolute Maximum Ratings (T<sub>A</sub>=25°C unless otherwise specified)**

| Parameter                                                      | Symbol           | Value       | Unit |
|----------------------------------------------------------------|------------------|-------------|------|
| Peak Pulse Power (8/20μs)                                      | P <sub>pk</sub>  | 300         | W    |
| Peak Pulse Current (8/20μs)                                    | I <sub>pp</sub>  | 20          | A    |
| ESD per IEC 61000-4-2 (Air)<br>ESD per IEC 61000-4-2 (Contact) | V <sub>ESD</sub> | ±30<br>±30  | kV   |
| Operating Temperature Range                                    | T <sub>J</sub>   | -55 to +125 | °C   |
| Storage Temperature Range                                      | T <sub>stg</sub> | -55 to +150 | °C   |

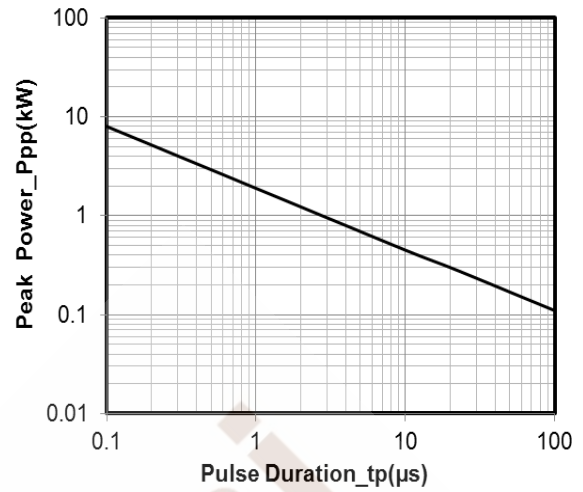
**Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise specified)**

| Parameter               | Symbol           | Min | Typ | Max | Unit | Test Condition                         |
|-------------------------|------------------|-----|-----|-----|------|----------------------------------------|
| Reverse Working Voltage | V <sub>RWM</sub> |     |     | 7   | V    |                                        |
| Breakdown Voltage       | V <sub>BR</sub>  | 7.5 |     |     | V    | I <sub>T</sub> = 1mA                   |
| Reverse Leakage Current | I <sub>R</sub>   |     |     | 0.5 | μA   | V <sub>RWM</sub> = 7V                  |
| Clamping Voltage        | V <sub>C</sub>   |     |     | 10  | V    | I <sub>PP</sub> = 1A (8 x 20μs pulse)  |
| Clamping Voltage        | V <sub>C</sub>   |     |     | 15  | V    | I <sub>PP</sub> = 20A (8 x 20μs pulse) |
| Junction Capacitance    | C <sub>J</sub>   |     |     | 60  | pF   | V <sub>R</sub> = 0V, f = 1MHz          |

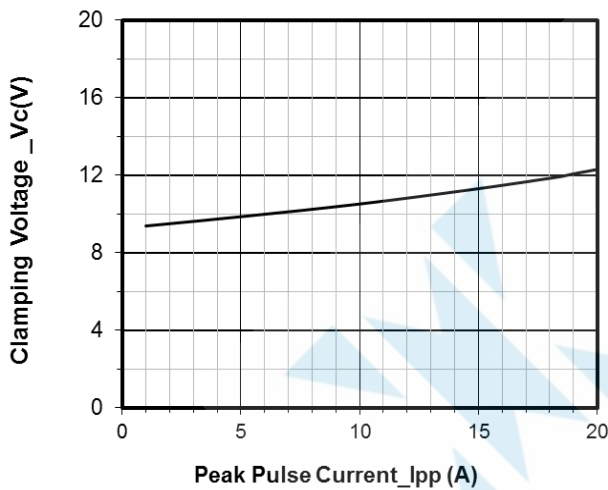
**Typical Performance Characteristics (TA=25°C unless otherwise Specified)**



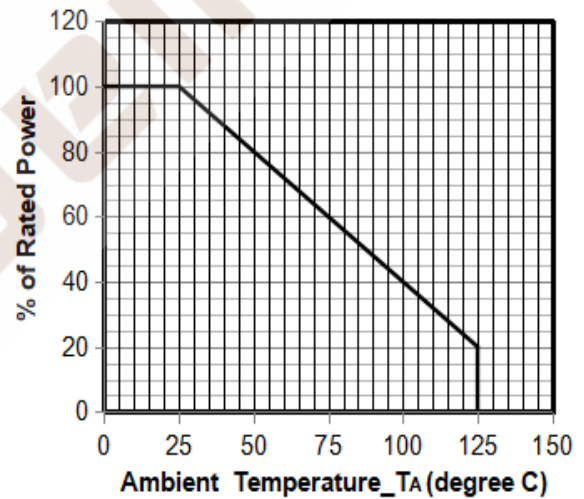
**Junction Capacitance vs. Reverse Voltage**



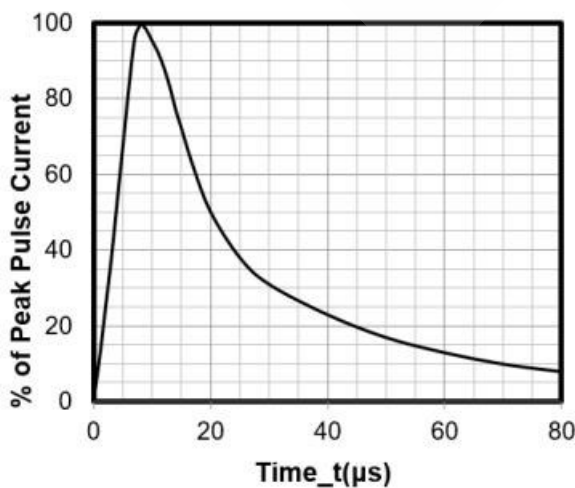
**Peak Pulse Power vs. Pulse Time**



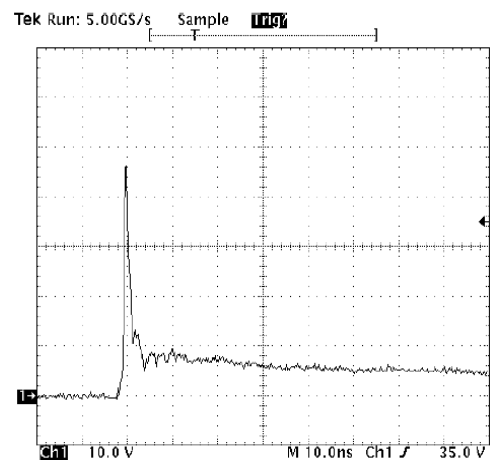
**Clamping Voltage vs. Peak Pulse Current**



**Power Derating Curve**



**8 X 20μs Pulse Waveform**

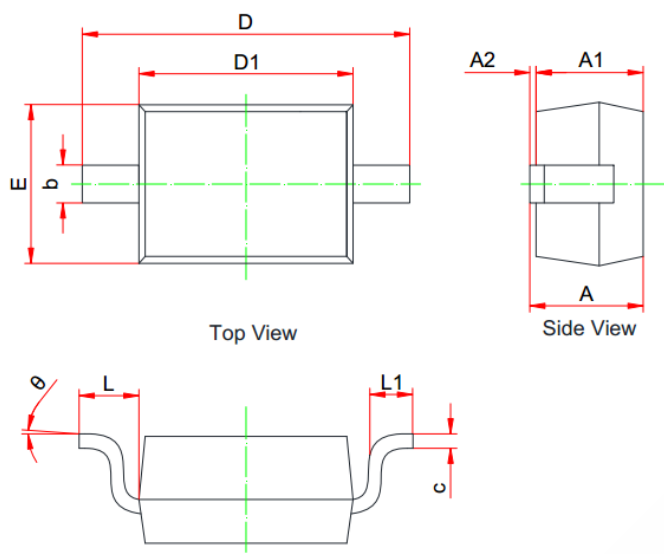


Note: Data is taken with a 10x attenuator

**ESD Clamping Voltage**

**8 kV Contact per IEC61000-4-2**

### SOD-323 Package Outline Drawing



|          | MILLIMETERS |       |       |
|----------|-------------|-------|-------|
|          | MIN         | NOM   | MAX   |
| A        | 0.800       | --    | 1.100 |
| A1       | 0.800       | --    | 0.900 |
| A2       | 0.000       | --    | 0.100 |
| b        | 0.250       | --    | 0.400 |
| c        | 0.080       | --    | 0.177 |
| D1       | 1.600       | 1.700 | 1.800 |
| D        | 2.300       | --    | 2.800 |
| E        | 1.150       | --    | 1.400 |
| L        | 0.475REF    |       |       |
| L1       | 0.100       | --    | 0.500 |
| $\Theta$ | 0°          | --    | 8°    |

### Suggested Land Pattern



Unit: mm

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